

An analysis for adhesive characteristics according to development of bonding system and compression method for duct bonding

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Key words : adhesive characteristics, bonding system

1. 가 (adhesive cohesive failure), 가 (adhesive interfacial failure), 가 (adherend failure)

Layer 가

3. 가 (mechanical joint) (adhesive bonding)

가 가 / 가

가

2. 가 weak bonding 가 가

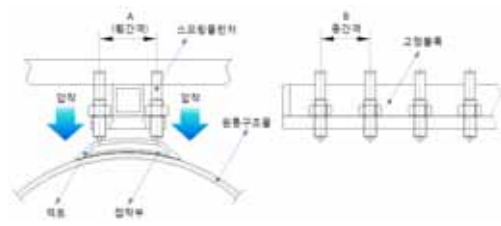


Fig. 1

가

가

4. FE Analysis

FE

Fig.2

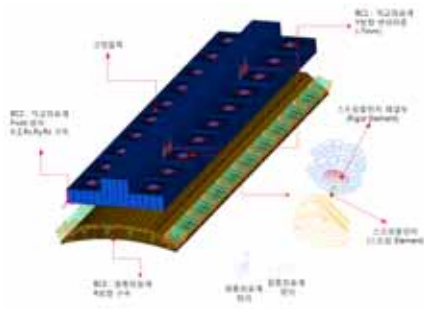


Fig. 2 FE

Fig.4
..2
force

reaction

Fig.4
50mm

가 1

node

0.87N

weak bonding

Fig.3

30mm

weak bonding

50mm

, 40mm

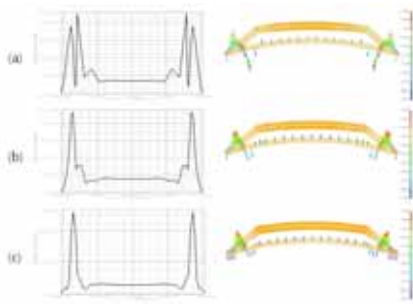


Fig. 3

34mm, (b)

44mm, (c)

(a) 50mm

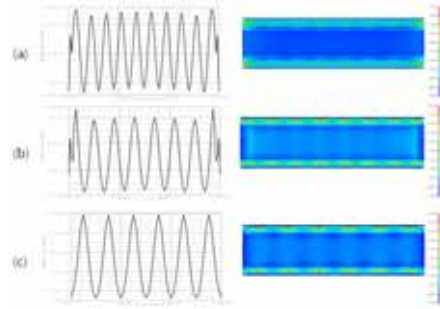


Fig. 4

30mm, (b)

40mm, (c)

(a)

50mm

Table 1

	30mm	40mm	50mm
(N)	0.85	1.0	1.2
(N)	0.58	0.45	0.33
(N)	0.27	0.55	0.87

5.

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